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## The Delphion Integrated View: INPADOC Record

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<b>Title:</b>	<b>CN1113921A: EPOXY RESIN COMPOSITE FOR PLASTIC SEALING SEMICONDUCTOR DEVICE AND ITS PREPARING METHOD</b>	 <a href="#">Hi</a> <a href="#">Re</a>															
<b>Derwent Title:</b>	Epoxy resin composite for plastic sealing semiconductor device <a href="#">[Derwent Record]</a>																
<b>Country:</b>	CN China																
<b>Kind:</b>	A Unexamined APPLIC. open to Public inspection																
<b>Inventor:</b>	SUN ZHONGXIAN; China LI GANG; China ZHANG JICHANG; China																
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<b>Published / Filed:</b>	1995-12-27 / 1994-06-02																
<b>Application Number:</b>	CN19949494105911																
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<b>ECLA Code:</b>	None																
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<b>Abstract:</b>	<p>The hydrolytic medium of the silane coupling agent of the present epoxy resin is the solution of ammonia water, through the regulation of acid-base degree of the solution of the silane coupling agent, the reactivity of silane coupling agent and the surface of silicon dioxide powder is strengthened, it makes an uniform monomolecular covering layer of the silane coupling agent be quickly formed on the surface of the silicon dioxide powder.</p>																
<b>INPADOC Legal Status:</b>	None	<a href="#">Get Now: Family Legal Status Report</a>															
<b>Family:</b>	<table border="1"> <thead> <tr> <th>PDF</th> <th>Publication</th> <th>Pub. Date</th> <th>Filed</th> <th>Title</th> </tr> </thead> <tbody> <tr> <td><input checked="" type="checkbox"/></td> <td>CN1113921A</td> <td>1995-12-27</td> <td>1994-06-02</td> <td>EPOXY RESIN COMPOSITE FOR PLASTIC SEALING SEMICONDUCTOR DEVICE AND ITS PREPARING METHOD</td> </tr> <tr> <td><input checked="" type="checkbox"/></td> <td>CN1036348B</td> <td>1997-11-05</td> <td>1994-06-02</td> <td>EPOXY RESIN COMPOSITION FOR PLASTIC SEALING SEMICONDUCTOR DEVICE AND ITS PREPARING METHOD</td> </tr> </tbody> </table> <p>2 family members shown above</p>		PDF	Publication	Pub. Date	Filed	Title	<input checked="" type="checkbox"/>	CN1113921A	1995-12-27	1994-06-02	EPOXY RESIN COMPOSITE FOR PLASTIC SEALING SEMICONDUCTOR DEVICE AND ITS PREPARING METHOD	<input checked="" type="checkbox"/>	CN1036348B	1997-11-05	1994-06-02	EPOXY RESIN COMPOSITION FOR PLASTIC SEALING SEMICONDUCTOR DEVICE AND ITS PREPARING METHOD
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<b>Other Abstract:</b>	None																